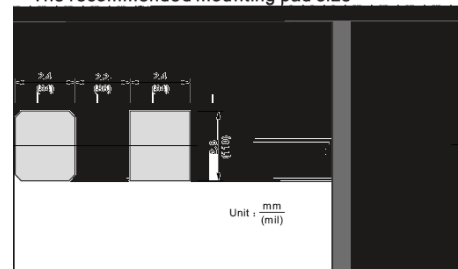




PIN	DESCRIPTION
1	Cathode
2	Anode

The recommended mounting pad size



									℃
									℃

Fig.1. Forward Current Derating Curve

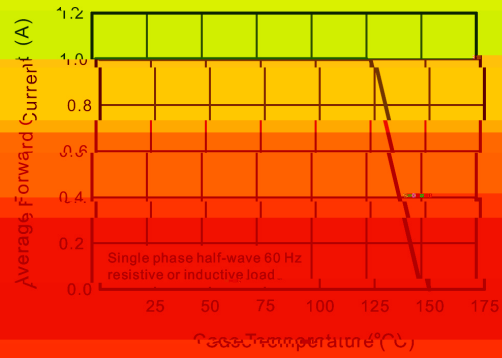


Fig.2 Typical Reverse Characteristics

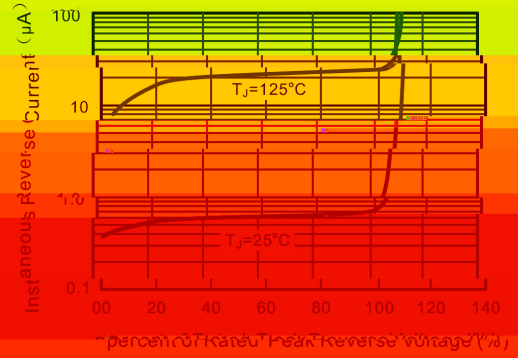
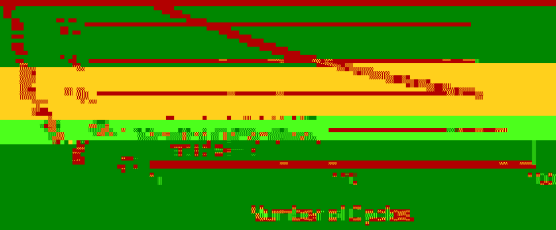


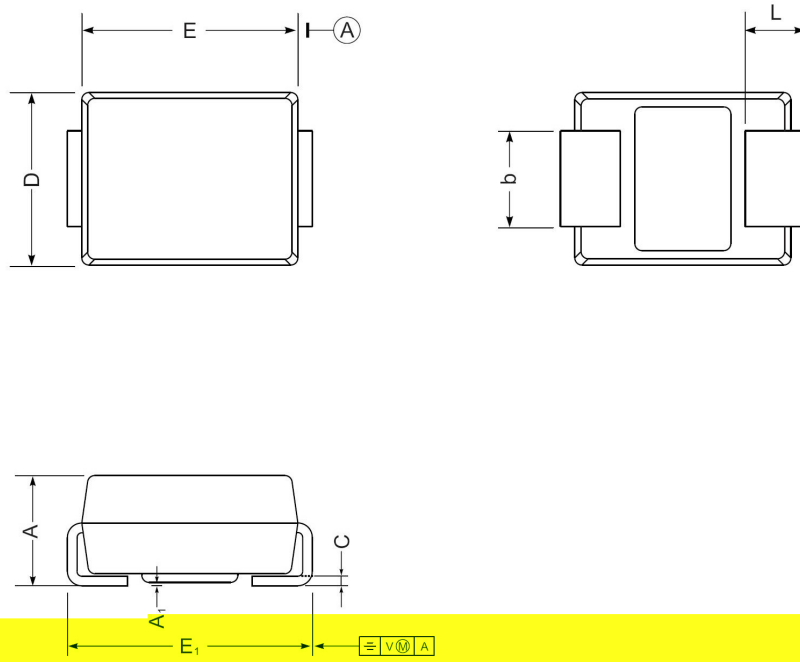
Fig.3 Typical Forward Characteristics



Fig.4 Maximum Non-Repetitive Peak



SMB

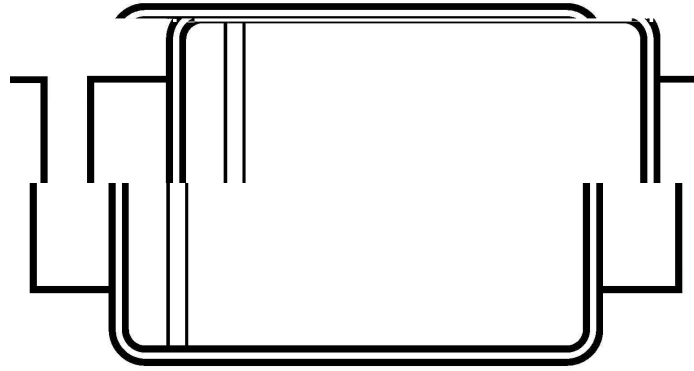


SMB mechanical data

UNIT		A	E	D	E ₁	A ₁	L	C	b
mm	max	2.44	4.70	3.94	5.59	0.20	1.5	0.305	2.2
	min	2.13	4.06	3.3	5.08	0.05	0.8	0.152	1.9
mil	max	96	185	155	220	7.9	59	12	87
	min	84	160	130	200	2.0	32	6	75

Marking

Type number	Marking code
US1AB	US1A
US1BB	US1B
US1DB	US1D
US1GB	US1G
US1JB	US1J
US1KB	US1K
US1MB	US1M



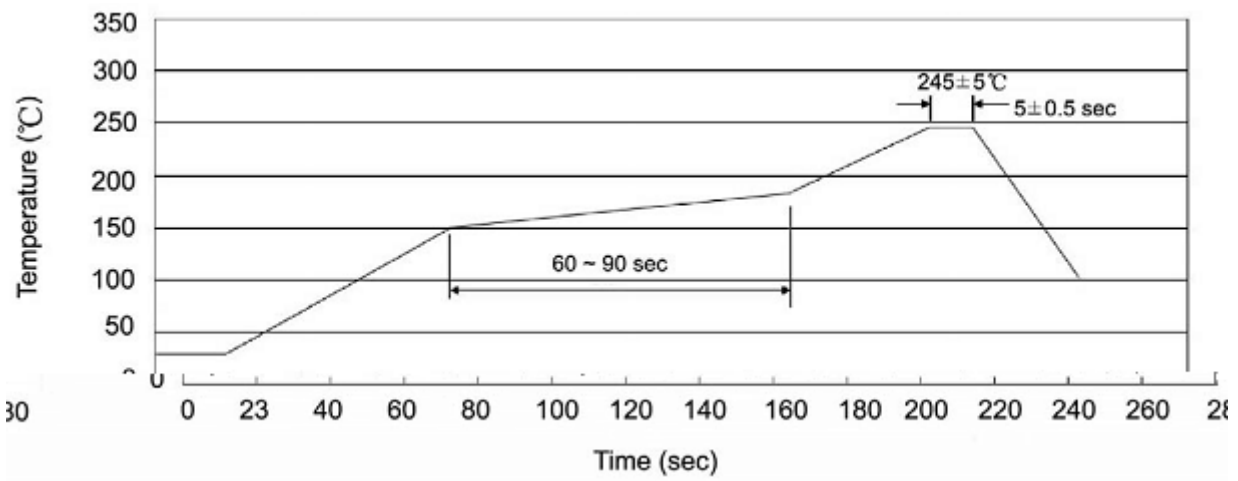
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Temperature Profile for IR Reflow Soldering(Pb-Free)



封装形式	包装数量					包装尺寸		
	只 卷盘	卷盘 盒	只 盒	盒 箱	只 箱		盒	箱